

Features

- Floating channel designed for bootstrap operation
- Fully operational to +200V
- Tolerant to negative transient voltage, dV/dt immune
- Gate drive supply range from 10V to 20V
- Undervoltage lockout
- 3.3V, 5V, and 15V logic compatible
- Cross-conduction prevention logic
- Matched propagation delay for both channels
- Internal set deadtime
- High-side output in phase with HIN input
- Low-side output out of phase with LIN input
- Leadfree, RoHS compliant
- Automotive qualified*

Typical Applications

- Pre-charge Switch Drives
- Stepper / Motor Drives
- DC-DC Converters

Product Summary

Topology	General Driver
V_{OFFSET}	$\leq 200\text{V}$
V_{OUT}	10V – 20V
$I_{\text{o+}} \ \& \ I_{\text{o-}}$ (typical)	290mA & 600mA
$t_{\text{on}} \ \& \ t_{\text{off}}$ (typical)	680ns & 150ns
Deadtime (typical)	520ns

Package Options



8 - Lead SOIC
AUIRS2003S

Diagram for DC-DC converter application

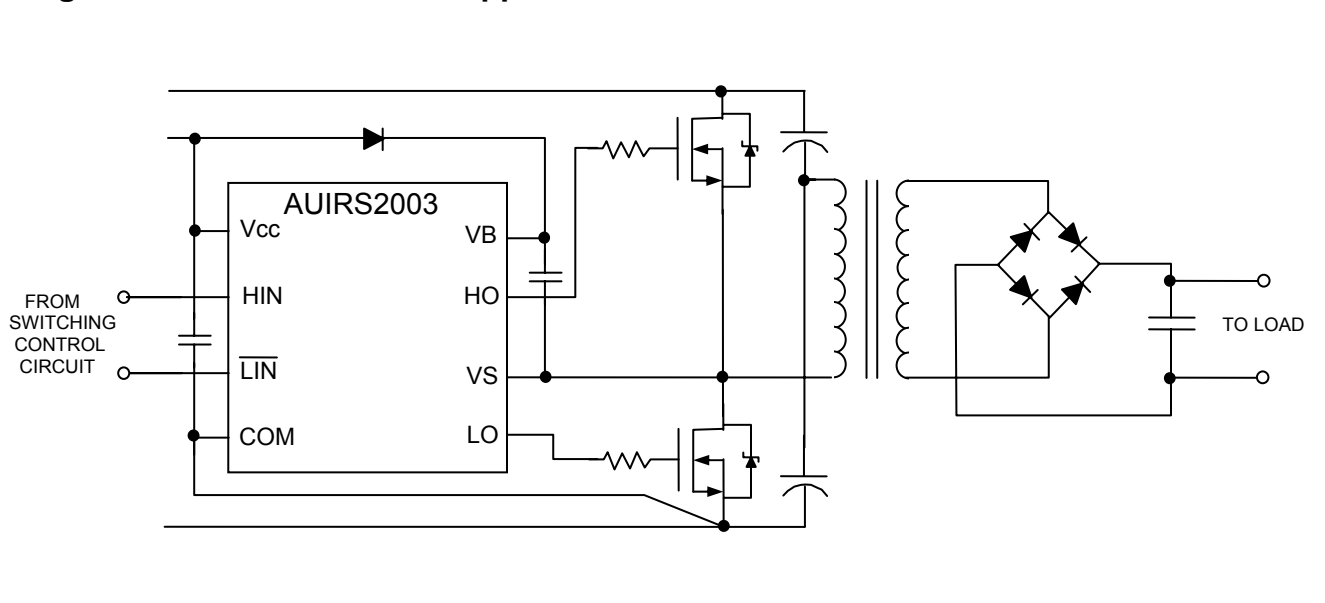
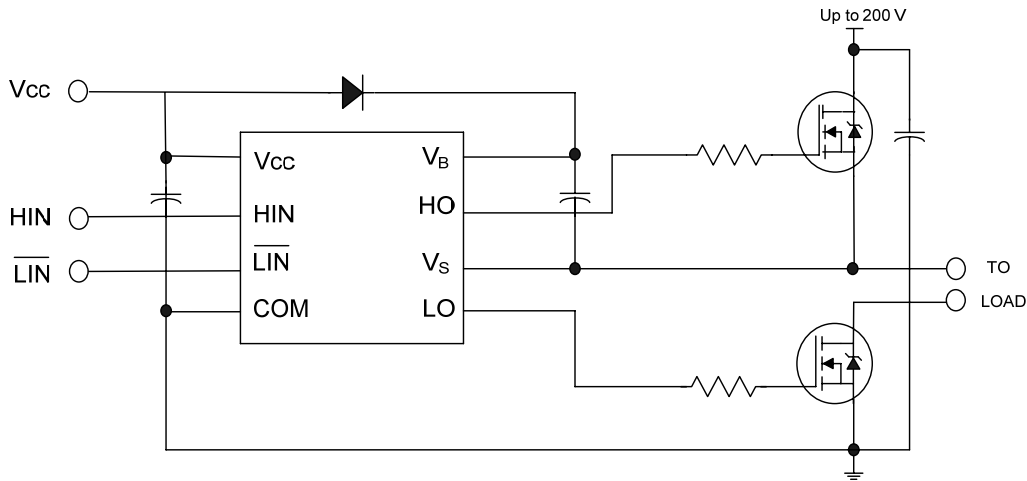


Table of Contents	Page
Typical Connection Diagram	1
Description/Feature Comparison	3
Qualification Information	4
Absolute Maximum Ratings	5
Recommended Operating Conditions	5
Static Electrical Characteristics	6
Dynamic Electrical Characteristics	6
Functional Block Diagram	7
Input/Output Pin Equivalent Circuit Diagram	8
Lead Definitions	9
Lead Assignments	9
Application Information and Additional Details	10
Package Details: SOIC8N	11
Package Details: SOIC8N, Tape and Reel	12
Part Marking Information	13
Ordering Information	14

Description

The AUIRS2003S is a high voltage, high speed power MOSFET and IGBT driver with dependent high and low side referenced output channels. Proprietary HVIC and latch immune CMOS technologies enable ruggedized monolithic construction. The logic input is compatible with standard CMOS or LSTTL output, down to 3.3V logic. The output drivers feature a high pulse current buffer stage designed for minimum driver cross-conduction. The floating channel can be used to drive an N-channel power MOSFET or IGBT in the high side configuration which operates up to 200V.

Typical Connection Diagram



(Refer to Lead Assignments for correct pin configuration). This/These diagram(s) show electrical connections only. Please refer to our Application Notes and Design Tips for proper circuit board layout.

Qualification Information[†]

Qualification Level		Automotive (per AEC-Q100 ^{††})	
		Comments: This family of ICs has passed an Automotive qualification. IR's Industrial and Consumer qualification level is granted by extension of the higher Automotive level.	
Moisture Sensitivity Level		SOIC8N	MSL3 ^{†††} 260°C (per IPC/JEDEC J-STD-020)
ESD	Machine Model	Class M2 (per AEC-Q100-003)	
	Human Body Model	Class H2 (per AEC-Q100-002)	
	Charged Device Model	Class C5 (per AEC-Q100-011)	
IC Latch-Up Test		Class II, Level B (per AEC-Q100-004)	
RoHS Compliant		Yes	

† Qualification standards can be found at International Rectifier's web site <http://www.irf.com/>

†† Exceptions to AEC-Q100 requirements are noted in the qualification report.

††† Higher MSL ratings may be available for the specific package types listed here. Please contact your International Rectifier sales representative for further information.

Absolute Maximum Ratings

Absolute Maximum Ratings indicate sustained limits beyond which damage to the device may occur. All voltage parameters are absolute voltages referenced to COM. The thermal resistance and power dissipation ratings are measured under board mounted and still air conditions.

Symbol	Definition	Min.	Max.	Units
V_B	High side floating absolute voltage	-0.3	225	V
V_S	High side floating supply offset voltage	$V_B - 25$	$V_B + 0.3$	
V_{HO}	High side floating output voltage	$V_S - 0.3$	$V_B + 0.3$	
V_{CC}	Low side and logic fixed supply voltage	-0.3	25	
V_{LO}	Low side output voltage	-0.3	$V_{CC} + 0.3$	
V_{IN}	Logic input voltage (HIN & LIN)	-0.3	$V_{CC} + 0.3$	
dV_S/dt	Allowable offset supply voltage transient	—	50	V/ns
P_D	Package power dissipation @ $T_A \leq 25^\circ\text{C}$	—	0.625	W
R_{thJA}	Thermal resistance, junction to ambient	—	200	$^\circ\text{C}/\text{W}$
T_J	Junction temperature	—	150	$^\circ\text{C}$
T_S	Storage temperature	-55	150	
T_L	Lead temperature (soldering, 10 seconds)	—	300	

Recommended Operating Conditions

The input/output logic timing diagram is shown in Fig 1. For proper operation the device should be used within the recommended conditions. The V_S offset rating is tested with all supplies biased at 15V differential.

Symbol	Definition	Min.	Max.	Units
V_B	High side floating supply absolute voltage	$V_S + 10$	$V_S + 20$	V
V_S	High side floating supply offset voltage	†	200	
V_{HO}	High side floating output voltage	V_S	V_B	
V_{CC}	Low side and logic fixed supply voltage	10	20	
V_{LO}	Low side output voltage	0	V_{CC}	
V_{IN}	Logic input voltage	0	V_{CC}	
T_A	Ambient temperature	-40	125	$^\circ\text{C}$

† Logic operational for V_S of -5V to +200V. Logic state held for V_S of -5V to $-V_{BS}$. (Please refer to the Design Tip DR97-3 for more details).

Dynamic Electrical Characteristics

$V_{CC} = V_{BS} = 15V$, $C_L = 1000pF$, $T_A = 25^\circ C$ unless otherwise specified.

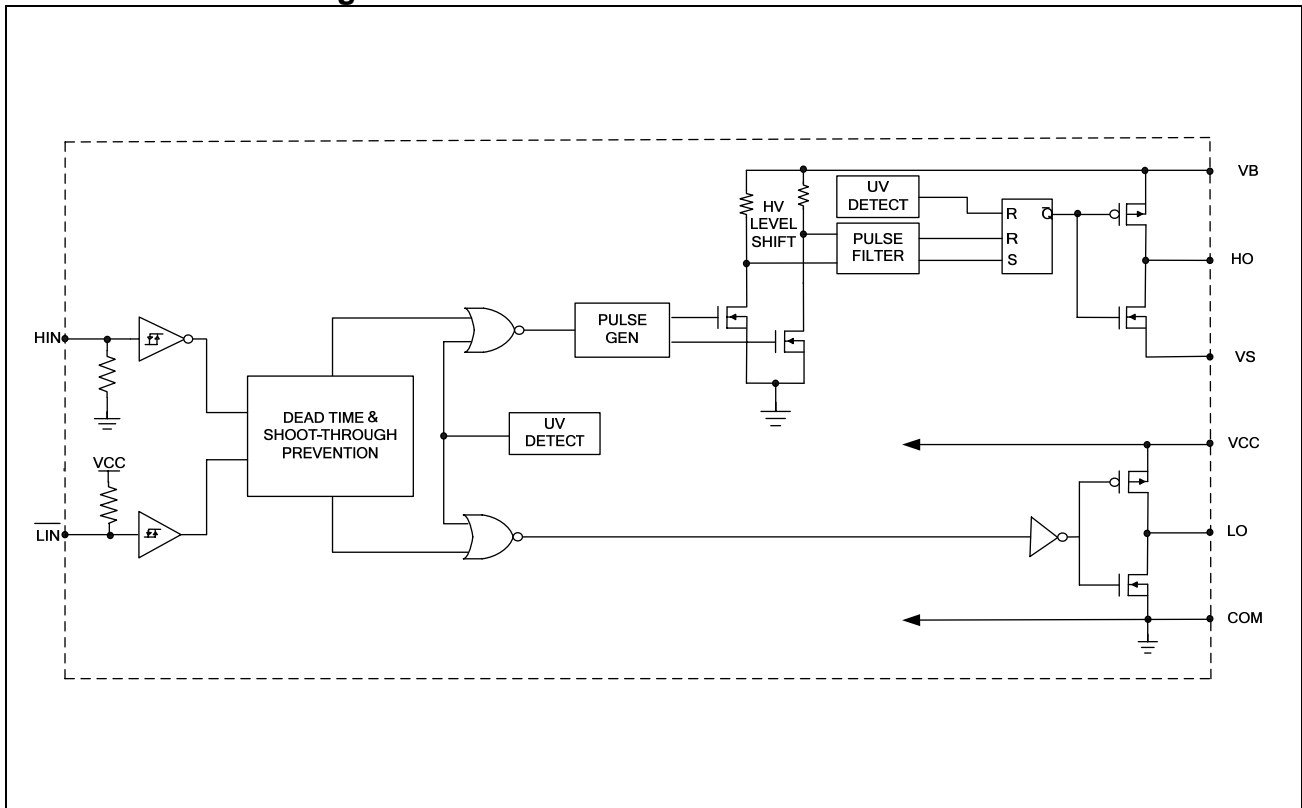
Symbol	Definition	Min	Typ	Max	Units	Test Conditions
t_{on}	Turn-on propagation delay	—	680	820	ns	$V_S = 0V$
t_{off}	Turn-off propagation delay	—	150	220		$V_S = 200V$
t_r	Turn-on rise time	—	70	170		
t_f	Turn-off fall time	—	35	90		
DT	Deadtime, LO turn-off to HO turn-on & HO turn-on to LO turn-off	400	520	650		
MT	Delay matching , HO & LO turn-on/off	—	—	60		

Static Electrical Characteristics

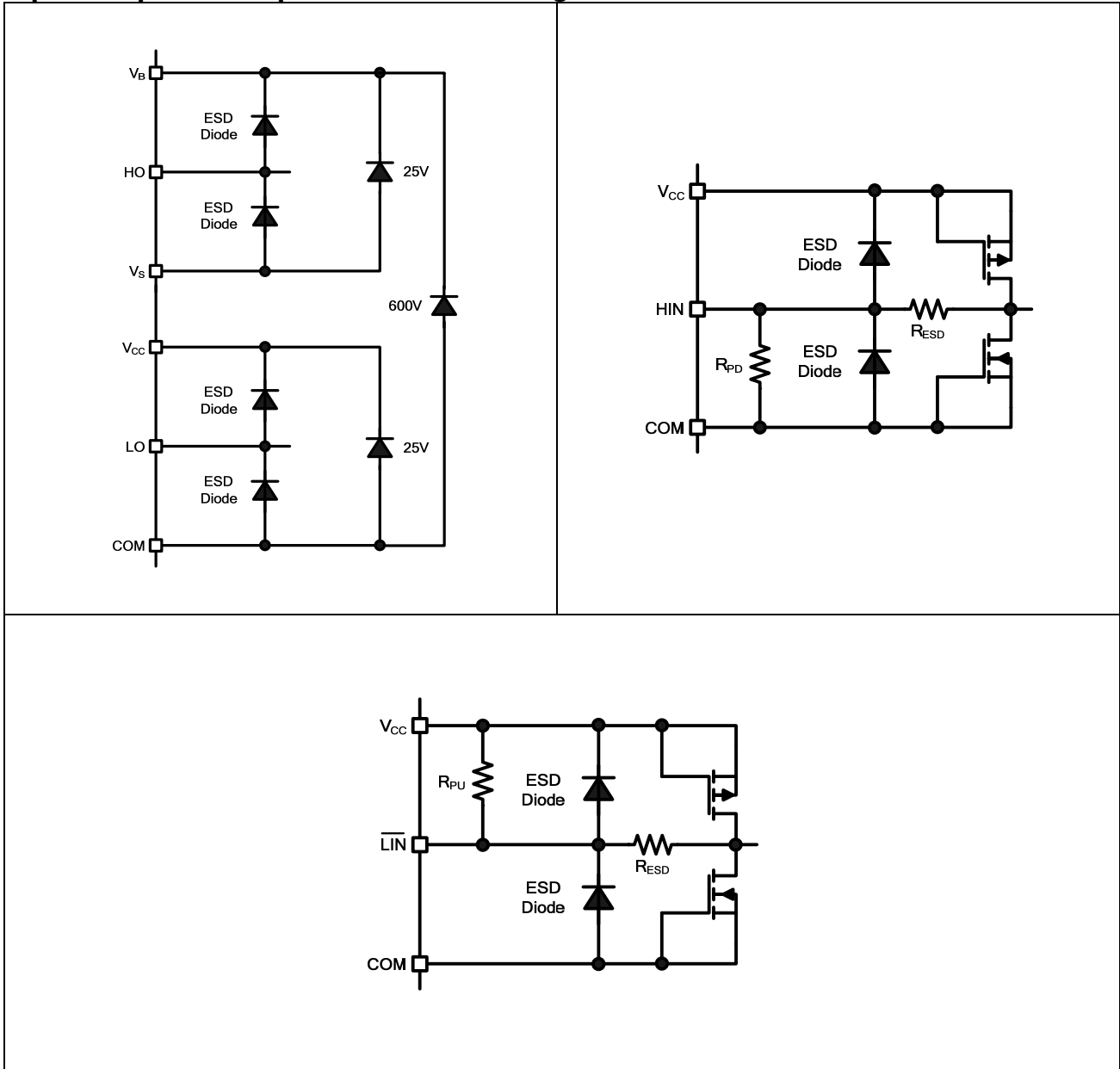
$V_{CC} = V_{BS} = 15V$ and $T_A = 25^\circ C$ unless otherwise specified. The V_{IN} and I_{IN} parameters are referenced to COM and are applicable to the input leads: HIN and LIN. The V_O and I_O parameters are referenced to COM and are applicable to the respective output leads: HO and LO.

Symbol	Definition	Min	Typ	Max	Units	Test Conditions
V_{IH}	Logic "1" input voltage	2.5	—	—	V	$V_{CC} = 10V$ to $20V$
V_{IL}	Logic "0" input voltage	—	—	0.8		
V_{OH}	High level output voltage, V_{CC} or $V_{BS} - V_O$	—	0.05	0.2		$I_O = 2mA$
V_{OL}	Low level output voltage, V_O	—	0.02	0.1		
I_{LK}	Offset supply leakage current	—	—	50	μA	$V_B = V_S = 200V$
I_{QBS}	Quiescent V_{BS} supply current	—	30	55		$V_{IN} = 0V$ or $5V$
I_{QCC}	Quiescent V_{CC} supply current	—	150	270		
I_{IN+}	Logic "1" input bias current	—	3	10		$V_{IN} = 5V$
I_{IN-}	Logic "0" input bias current	—	—	5		$V_{IN} = 0V$
V_{CCUV+} V_{BSUV+}	V_{CC} and V_{BS} supply undervoltage positive going threshold	8.0	8.9	9.8	V	
V_{CCUV-} V_{BSUV-}	V_{CC} and V_{BS} supply undervoltage negative going threshold	7.4	8.2	9.0		
I_{O+}	Output high short circuit pulsed current	130	290	—	mA	$V_O = 0V$, $V_{IN} = V_{IH}$ $PW \leq 10 \mu s$
I_{O-}	Output low short circuit pulsed current	270	600	—		$V_O = 15V$, $V_{IN} = V_{IL}$ $PW \leq 10 \mu s$

Functional Block Diagram



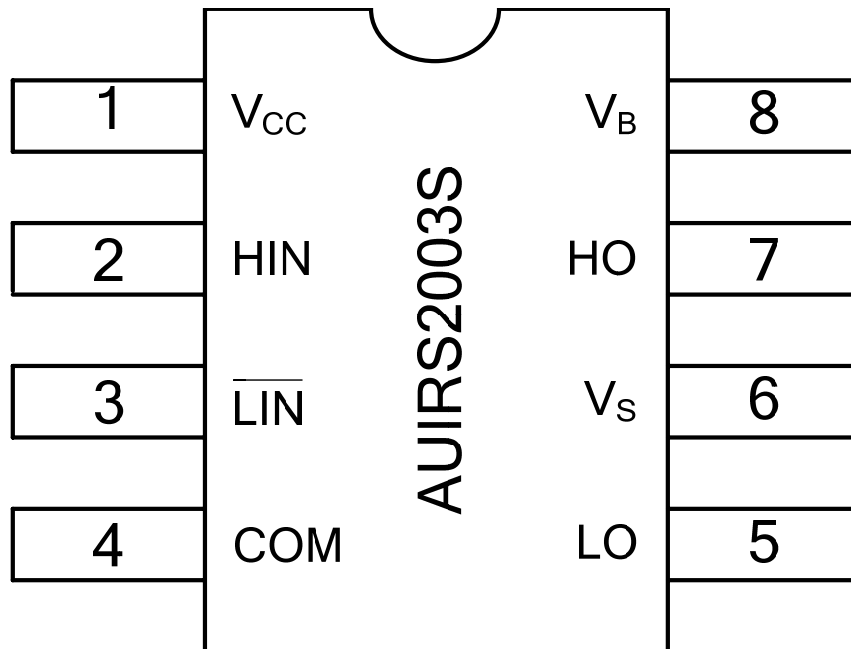
Input/Output Pin Equivalent Circuit Diagrams



Lead Definitions

PIN	Symbol	Description
1	V_{CC}	Low side and logic fixed supply
2	HIN	Logic input for high side gate driver output (HO), in phase
3	\overline{LIN}	Logic input for low side driver output (LO), out of phase
4	COM	Low side return
5	LO	Low side gate drive output
6	V_S	High side floating supply return
7	HO	High side gate drive output
8	V_B	High side floating supply

Lead Assignments



Application Information and Additional Details

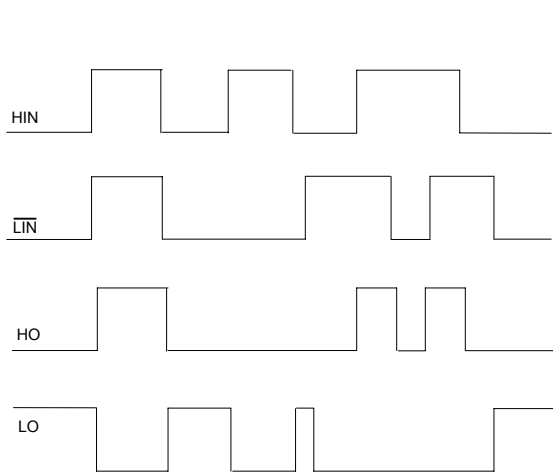


Figure 1: Input/Output Timing Diagram

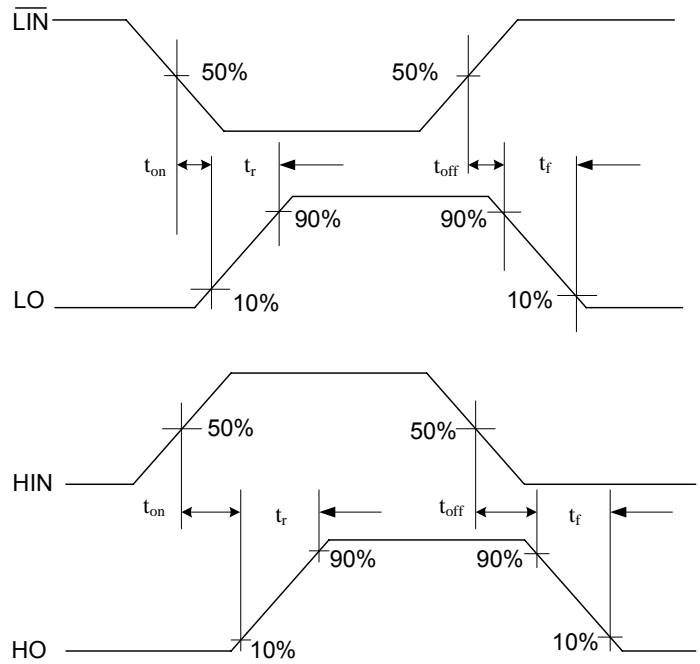


Figure 2: Switching Time Waveform Definition

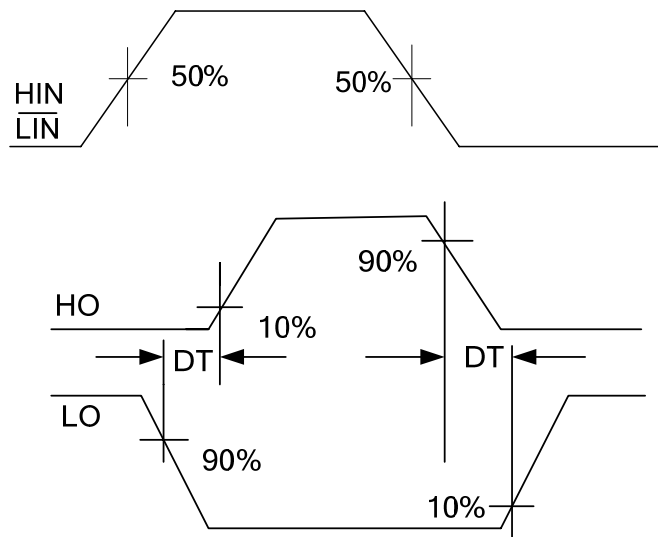
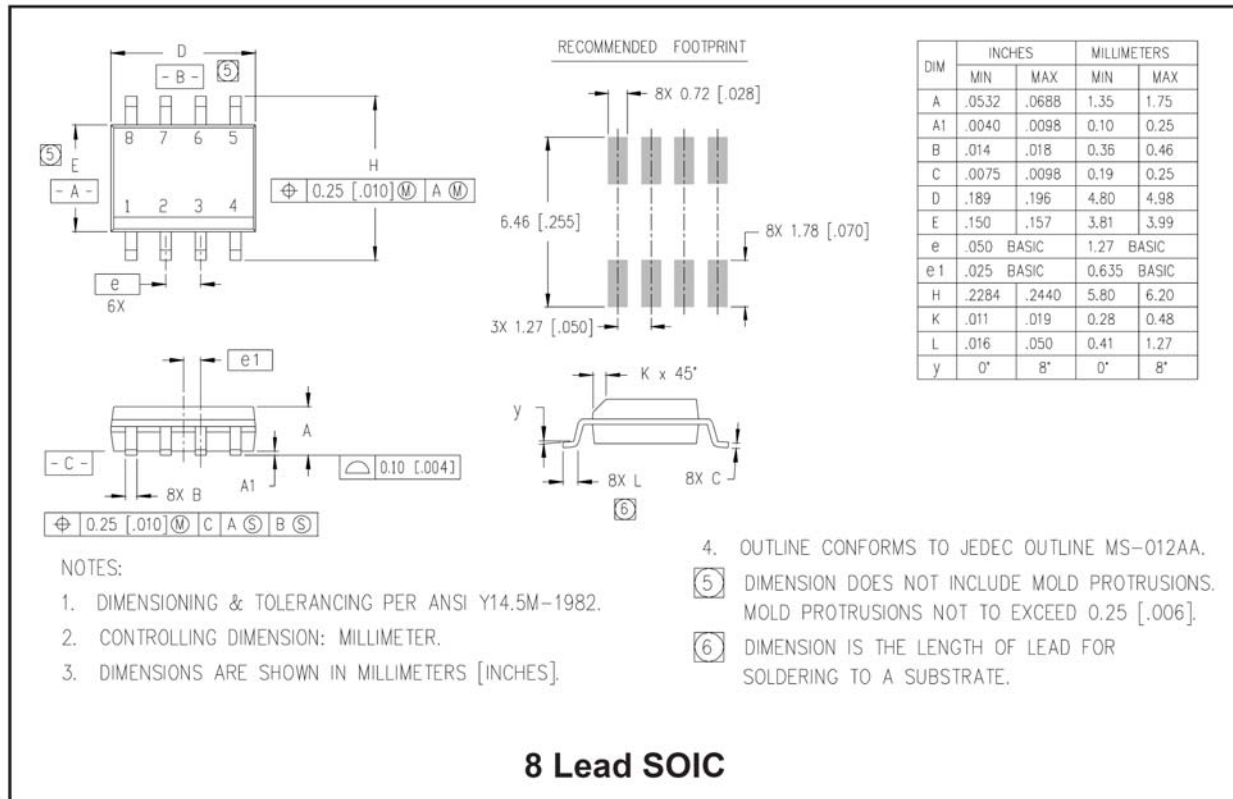


Figure 3: Delay Matching Waveform Definitions

Package Details: SOIC8N

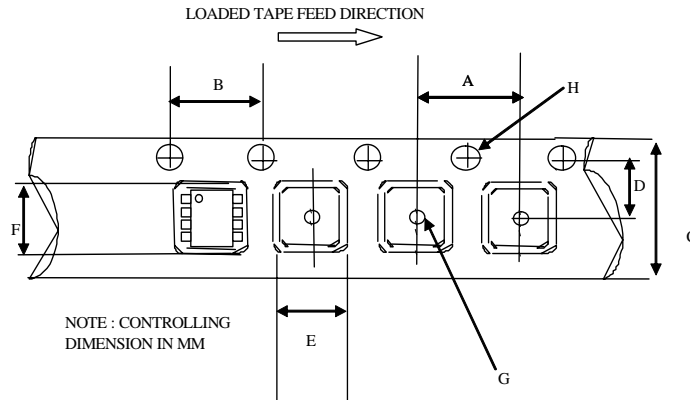


NOTES:

1. DIMENSIONING & TOLERANCING PER ANSI Y14.5M-1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSIONS ARE SHOWN IN MILLIMETERS [INCHES].

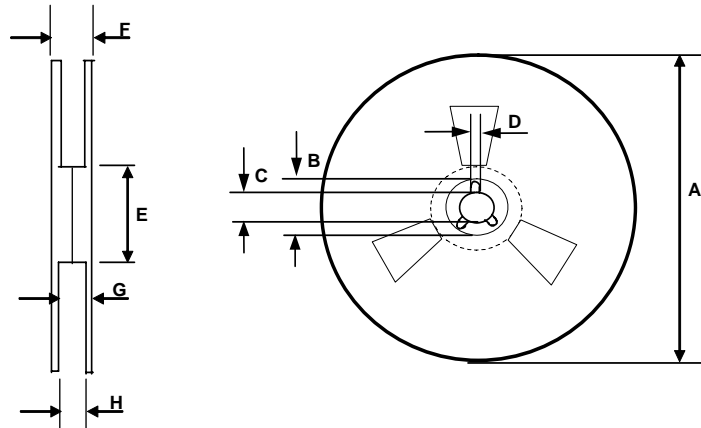
4. OUTLINE CONFORMS TO JEDEC OUTLINE MS-012AA.
5. DIMENSION DOES NOT INCLUDE MOLD PROTRUSIONS. MOLD PROTRUSIONS NOT TO EXCEED 0.25 [.006].
6. DIMENSION IS THE LENGTH OF LEAD FOR SOLDERING TO A SUBSTRATE.

Package Details: SOIC8N, Tape and Reel



CARRIER TAPE DIMENSION FOR 8SOICN

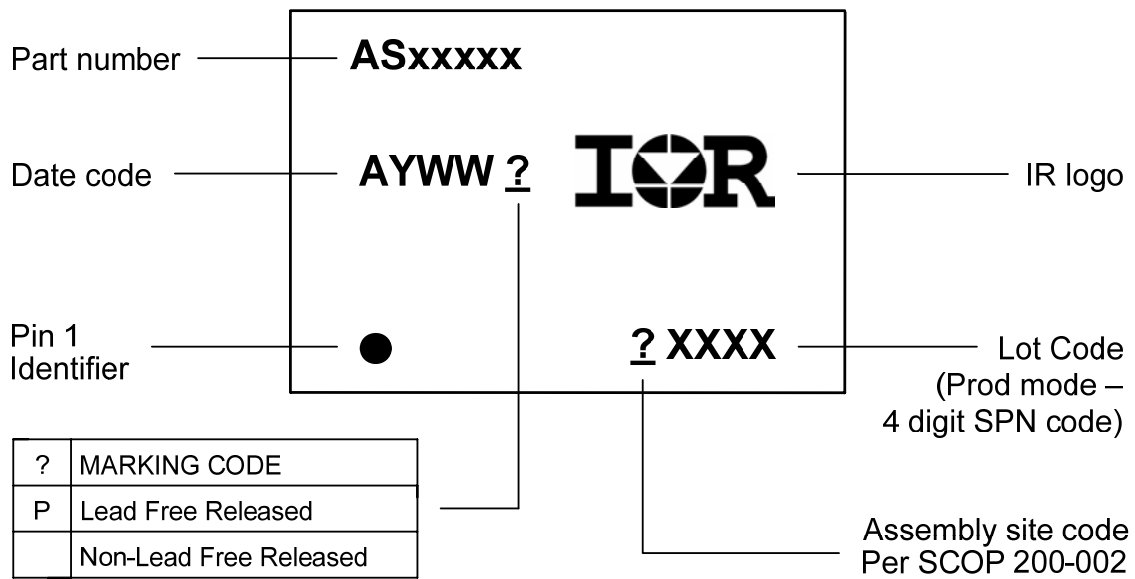
Code	Metric		Imperial	
	Min	Max	Min	Max
A	7.90	8.10	0.311	0.318
B	3.90	4.10	0.153	0.161
C	11.70	12.30	0.46	0.484
D	5.45	5.55	0.214	0.218
E	6.30	6.50	0.248	0.255
F	5.10	5.30	0.200	0.208
G	1.50	n/a	0.059	n/a
H	1.50	1.60	0.059	0.062



REEL DIMENSIONS FOR 8SOICN

Code	Metric		Imperial	
	Min	Max	Min	Max
A	329.60	330.25	12.976	13.001
B	20.95	21.45	0.824	0.844
C	12.80	13.20	0.503	0.519
D	1.95	2.45	0.767	0.096
E	98.00	102.00	3.858	4.015
F	n/a	18.40	n/a	0.724
G	14.50	17.10	0.570	0.673
H	12.40	14.40	0.488	0.566

Part Marking Information



Ordering Information

Base Part Number	Package Type	Standard Pack		Complete Part Number
		Form	Quantity	
AUIRS2003S	SOIC8	Tube/Bulk	95	AUIRS2003S
		Tape and Reel	2500	AUIRS2003STR

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Revision History

Date	Comment
5/12/08	Tables modified for AUIRS2003
8/20/08	Added cross conduction prevention comment to IC features Changed product summary topology to "General Driver" Changed product summary I _{O+} & I _{O-} units from A to mA Modified functional block diagram to include the deadtime and shoot-through protection Added V _{BSUV+} and V _{BSUV-} parameters Added input/output pin equivalent circuit diagrams Added IC label on lead assignment block Updated waveform diagrams to reflect proper labeling Reviewed all text/diagrams to reflect proper reference to LIN
10/13/08	Updated LU rating to Class II level B (due to input pins having LU<100mA)
10/20/08	Reformatted I/O table Edited lead assignment dwg Deleted parameter trends place holder Removed coloration n functional block dwg Removed unnecessary "AUIRS2003S" label in typical connection dwg, functional block dwg, lead assignment dwg Updated table of contents Updated MM rating to Class A based on latest ESD data
10/23/08	Updated MSL rating from 2 to 3 Updated ESD and LU classification to Q100
1/20/09	Changes from APBU: Added Typical Application list – P1 Added Diagram for DC-DC converter application, and moved Typical Connection Diagram to P3
1/28/09	Reviewed by Scott, Preliminary sign removed
9/21/09	Change part description on front page to "Half-Bridge Driver" from "High and Low Side driver".